Product End-of-Life Disassembly Instructions

Product Category: Storage Enclosures
Marketing Name / Model **[List multiple models if applicable.]**
Name / Model #1 QL340A 3PAR Service Processor , QL340B HP 3PAR Service Processor
Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm 1	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	**Tool Size (if applicable)**
Description #1 Screw driver tip size #4 and #6.	
Description #2	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the two side rails using 5 rail screws (SCR, M4x0.7x6mm) on each side. Torque specification = 17.8 IN-LBS.
2. Open the top Chassis cover and remove the Air Shroud.
3. Remove the CPU heatsink. The required torque on the screwdriver to remove the CPU heatsink is: 6.94 in./lb
4. Remove the P4D-E1500-220-512K800 CPU and two pieces of MEM-DR220L-CL03-EU6 from DIMM1A and DIMM1B.
5. Remove two screws to disassemble the riser card from the chassis.
6. Remove the cable such as SATA/USB from the system.
7. Remove the intrusion cable from JL1 on the motherboard
8. Untie the cable connecting to the motherboard and remove them from the motherboard.
9. Remove the DVD power cable from the P3 connector from the power supply and remove the SATA power cable from the P4 connector from the power supply.
10. Remove Front Control Panel Cable from JF1 on the motherboard
11. Remove the left fan from FAN1 on the motherboard and remove the right fan.
12. Remove 8 screws to release the motherboard from the chassis
13. Remove the CPU retention bracket from the motherboard.
14. Remove the RSC-RR1U-32L from the riser card bracket.
15. Remove the hard drive tray from the chassis by removing one screw.
16. Remove 4 of the screws attached to the HDD-T0500-WD5002ABYS hard drive from the hard drive tray. Per Western Digital, torque on the screwdriver will be set to the recommended 5 in./lb when un-installing the 4 screws from the hard drive to the tray.
17. Remove the DVM-PNSC-824B DVD drive from the bracket and unsecure from the chassis
18. Note: Unless otherwise noted, all screwdrivers for this SP will have a torque between 6-8 IN-LBS.
19. The system is now disassembled.
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26.

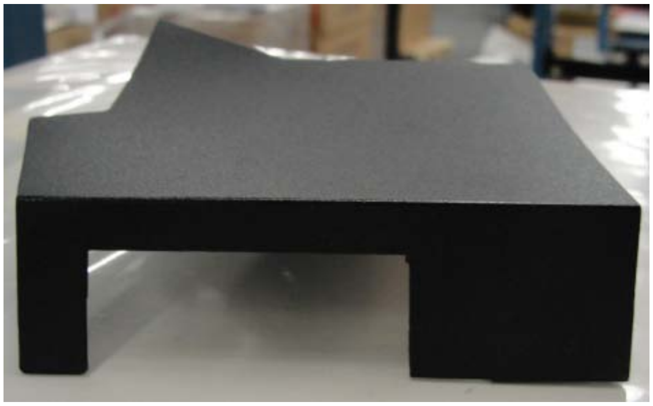
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

a- Unless otherwise noted, all screwdrivers for this SP will have a torque between 6-8 IN-LBS.
b- Special torque requirements are for: Hard Drive screws, heatsink screws, and rail screws.
c- The required torque on the screwdriver to install/de-install the CPU heatsink is: **6.94 in./lb**
d- Screw driver tip size #4 and #6.

Instruction pictures:

1) Remove the two side rails using 5 rail screws (SCR, M4x0.7x6mm) on each side. Torque specification = 17.8 IN-LBS

2)



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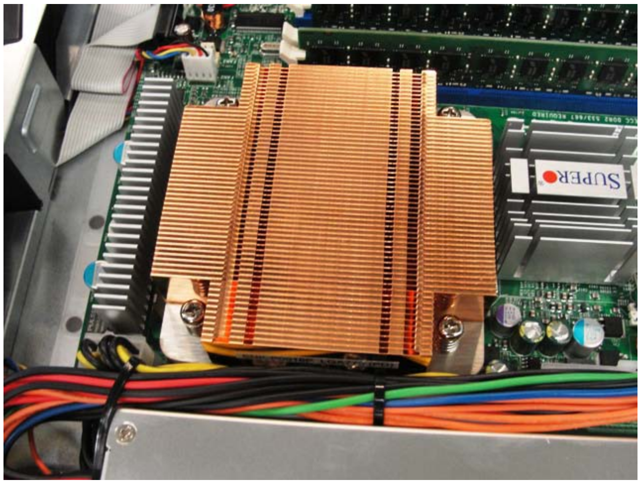

PSG instructions for this template are available at EL-MF877-01

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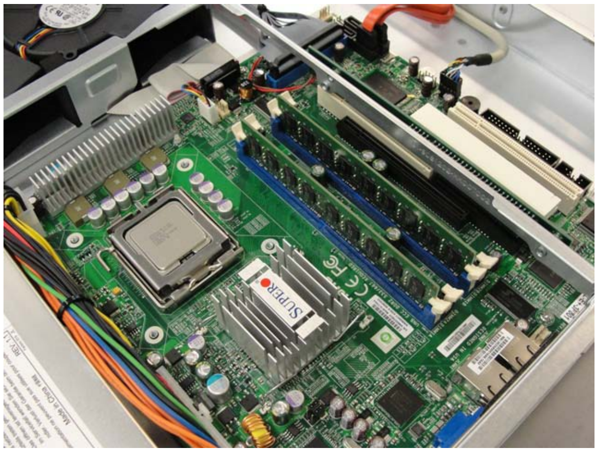

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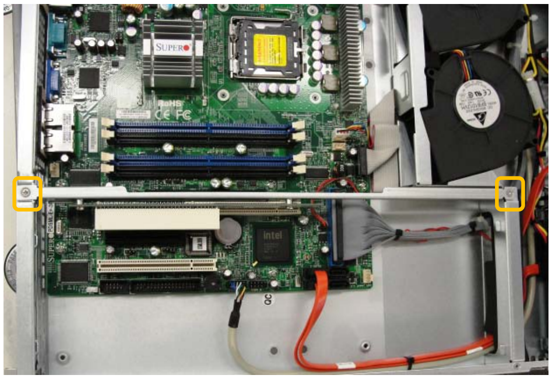

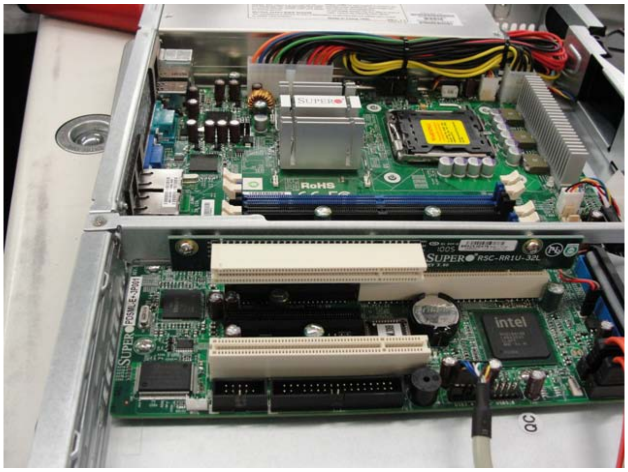

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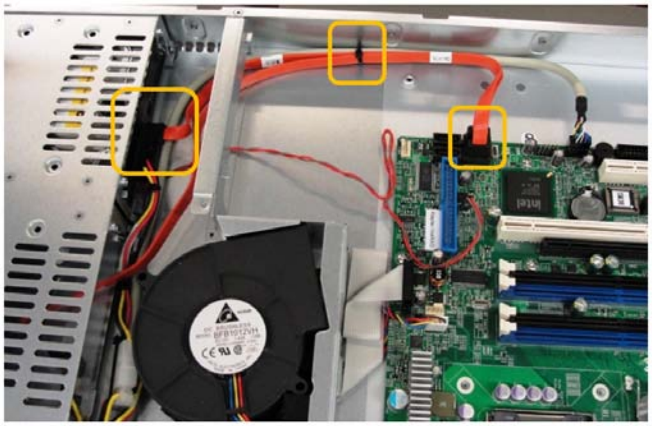

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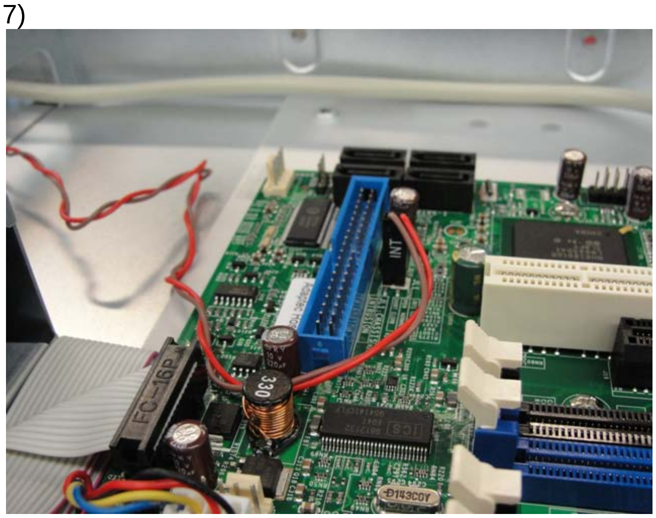

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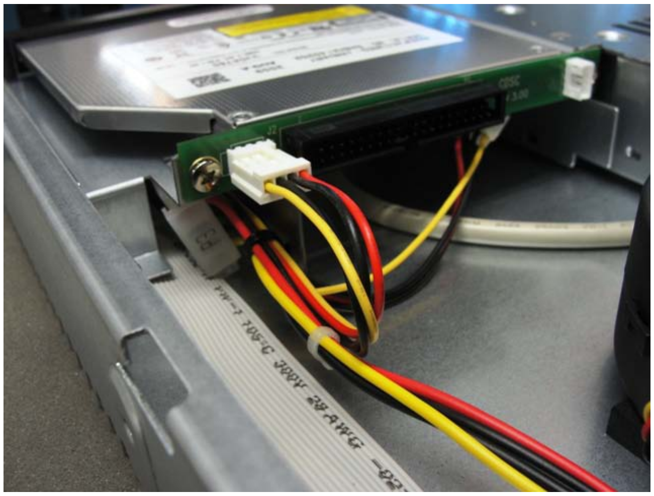

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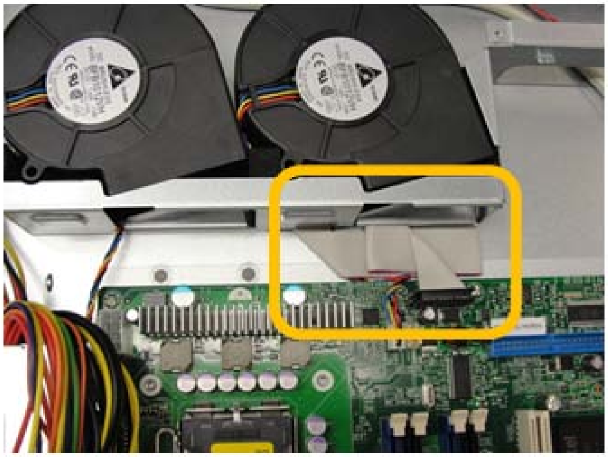

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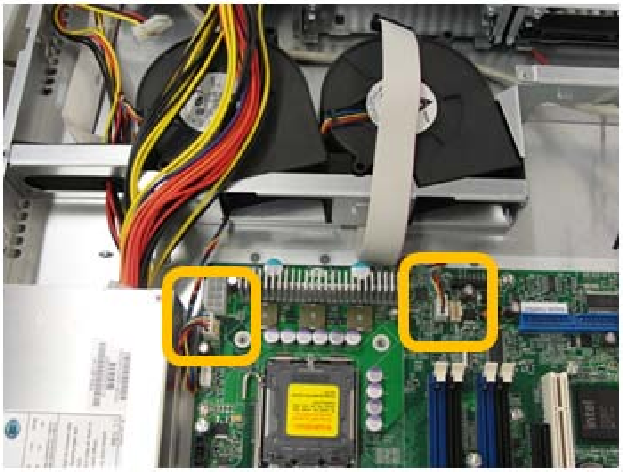

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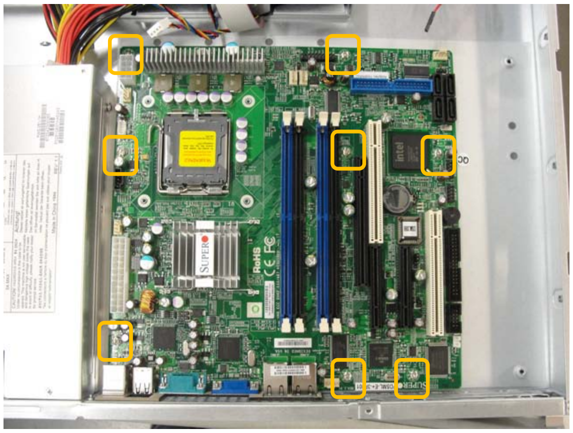

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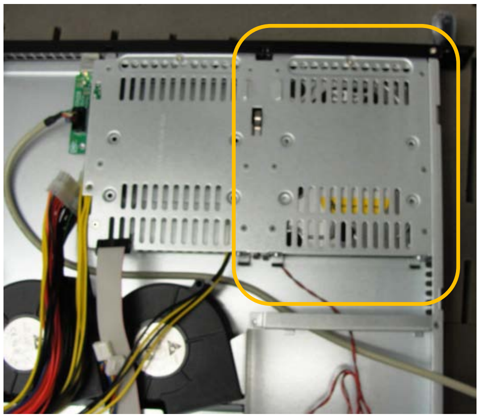

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18) Note: Unless otherwise noted, all screwdrivers for this SP will have a torque between 6-8 IN-LBS.

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